

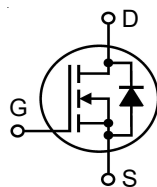
X2-Class Power MOSFET

IXTQ48N65X2M

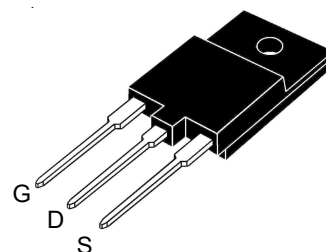
$$\begin{aligned} V_{DSS} &= 650V \\ I_{D25} &= 48A \\ R_{DS(on)} &\leq 65m\Omega \end{aligned}$$

(Electrically Isolated Tab)

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



OVERMOLDED
(IXTQ...M)



G = Gate D = Drain
S = Source

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ\text{C to } 150^\circ\text{C}$	650	V
V_{DGR}	$T_J = 25^\circ\text{C to } 150^\circ\text{C}, R_{GS} = 1\text{ M}\Omega$	650	V
V_{GSS}	Continuous	± 30	V
V_{GSM}	Transient	± 40	V
I_{D25}	$T_C = 25^\circ\text{C}$, Limited by T_{JM}	48	A
I_{DM}	$T_C = 25^\circ\text{C}$, Pulse Width Limited by T_{JM}	70	A
I_A	$T_C = 25^\circ\text{C}$	20	A
E_{AS}	$T_C = 25^\circ\text{C}$	1.5	J
dv/dt	$I_S \leq I_{DM}, V_{DD} \leq V_{DSS}, T_J = 150^\circ\text{C}$	15	V/ns
P_D	$T_C = 25^\circ\text{C}$	70	W
T_J		- 55 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		- 55 ... +150	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering 1.6 mm (0.062 in.) from Case for 10s	300	$^\circ\text{C}$
V_{ISOL}	50/60 Hz, 1 Minute	2500	V~
M_d	Mounting Torque	1.13/10	Nm/lb.in
Weight		5	g

Features

- Plastic Overmolded Tab for Electrical Isolation
- Avalanche Rated
- Fast Intrinsic Diode
- 2500V~ Electrical Isolation
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- Laser Drivers
- AC and DC Motor Drives
- Robotics and Servo Controls

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0V, I_D = 1mA$	650		V
$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	3.0		5.0 V
I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$			$\pm 100\text{ nA}$
I_{DSS}	$V_{DS} = V_{DSS}, V_{GS} = 0V$ $T_J = 125^\circ\text{C}$			10 μA 200 μA
$R_{DS(on)}$	$V_{GS} = 10V, I_D = 0.5 \cdot I_{D25}$, Note 1			65 m Ω

Symbol	Test Conditions (T _J = 25°C, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max
g_{fs}	V _{DS} = 10V, I _D = 0.5 • I _{D25} , Note 1	24	40	S
R_{Gi}	Gate Input Resistance		1.2	Ω
C_{iss}	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz		4300	pF
C_{oss}			3280	pF
C_{rss}			6.4	pF
Effective Output Capacitance				
C_{o(er)}	Energy related	V _{GS} = 0V V _{DS} = 0.8 • V _{DSS}	150	pF
C_{o(tr)}	Time related		665	pF
t_{d(on)}	Resistive Switching Times V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 0.5 • I _{D25} R _G = 3Ω (External)		19	ns
t_r			26	ns
t_{d(off)}			50	ns
t_f			15	ns
Q_{g(on)}	V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 0.5 • I _{D25}		76	nC
Q_{gs}			22	nC
Q_{gd}			28	nC
R_{thJC}				1.78 °C/W
R_{thCS}			0.25	°C/W

Source-Drain Diode

Symbol	Test Conditions ($T_J = 25^{\circ}\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max
I_S	$V_{GS} = 0\text{V}$			48 A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			192 A
V_{SD}	$I_F = I_S$, $V_{GS} = 0\text{V}$, Note 1			1.4 V
t_{rr}	$I_F = 24\text{A}$, $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}$		400	ns
Q_{RM}			6	μC
I_{RM}			30	A

Note 1. Pulse test, $t \leq 300\mu\text{s}$, duty cycle, $d \leq 2\%$.

Littelfuse Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338 B2
4,860,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

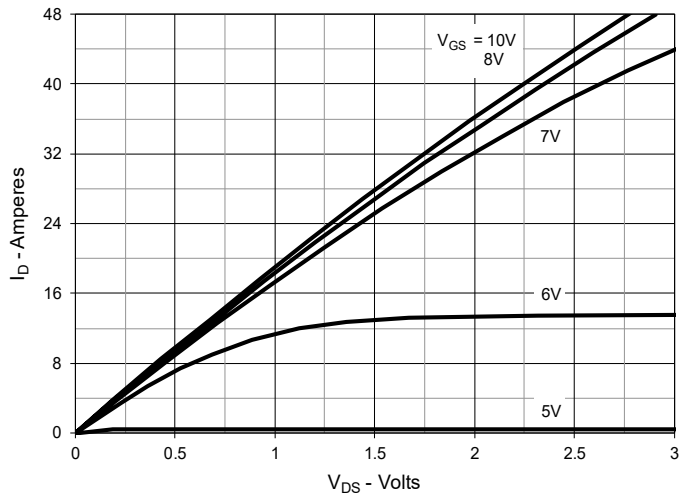
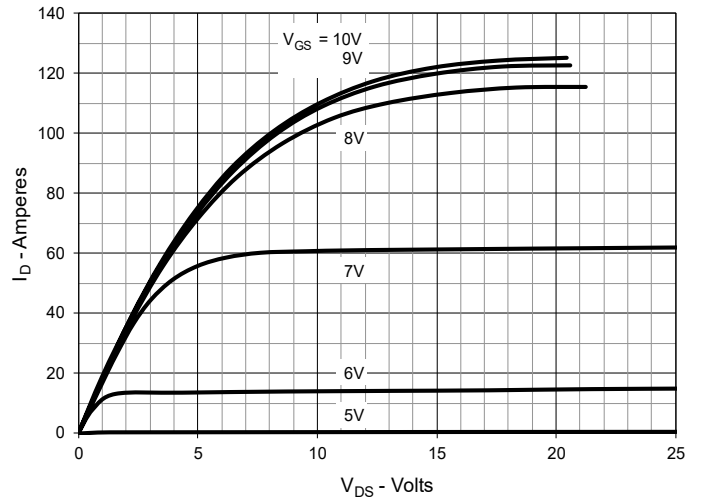
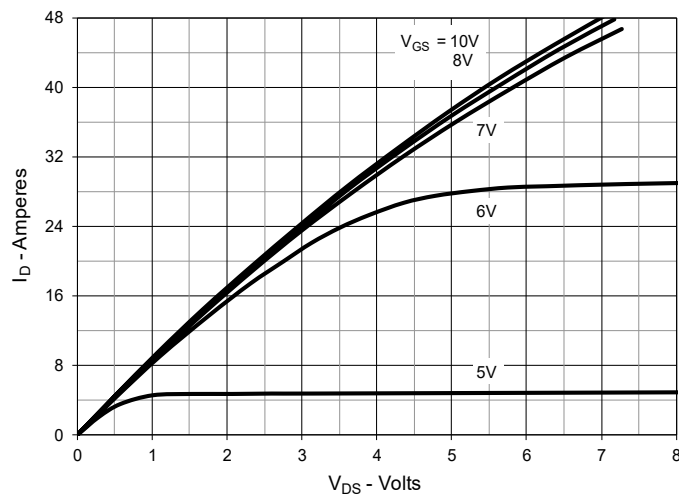
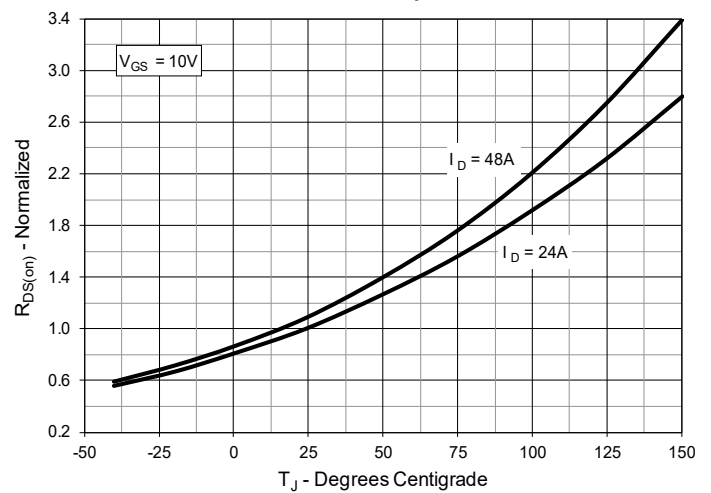
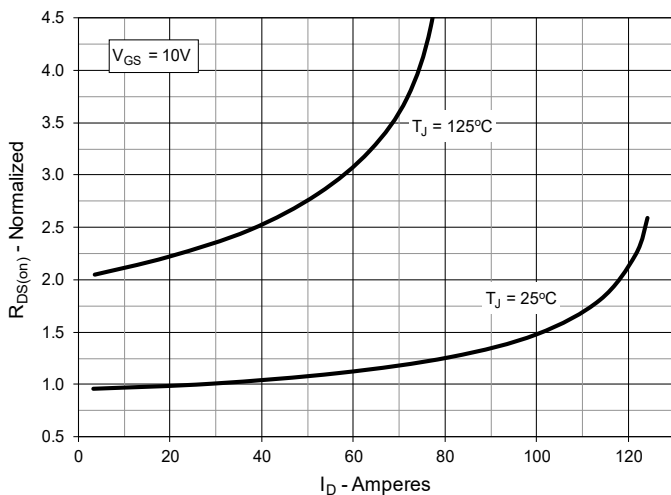
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$ Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$ Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$ Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 24\text{A}$ Value vs. Junction TemperatureFig. 5. $R_{DS(on)}$ Normalized to $I_D = 24\text{A}$ Value vs. Drain Current

Fig. 6. Normalized Breakdown & Threshold Voltages vs. Junction Temperature

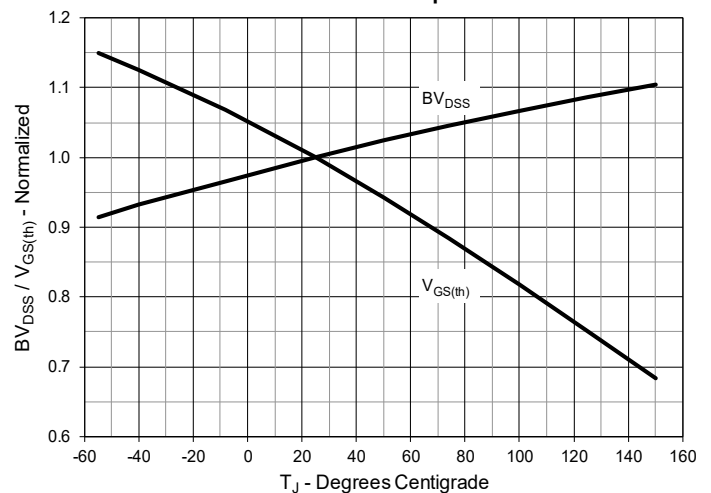


Fig. 7. Input Admittance

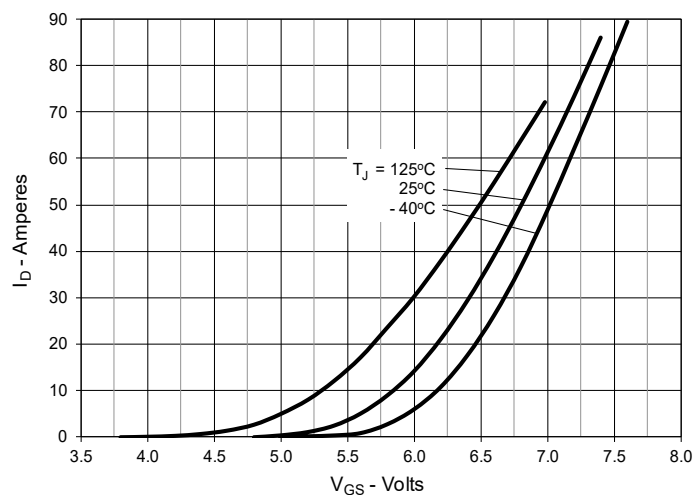


Fig. 8. Transconductance

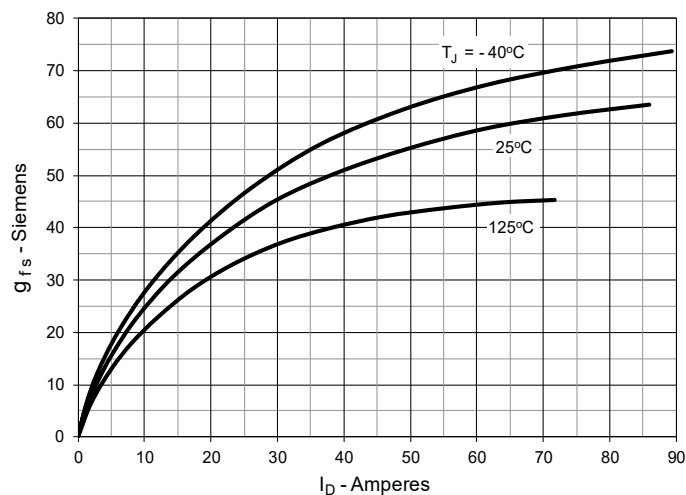


Fig. 9. Forward Voltage Drop of Intrinsic Diode

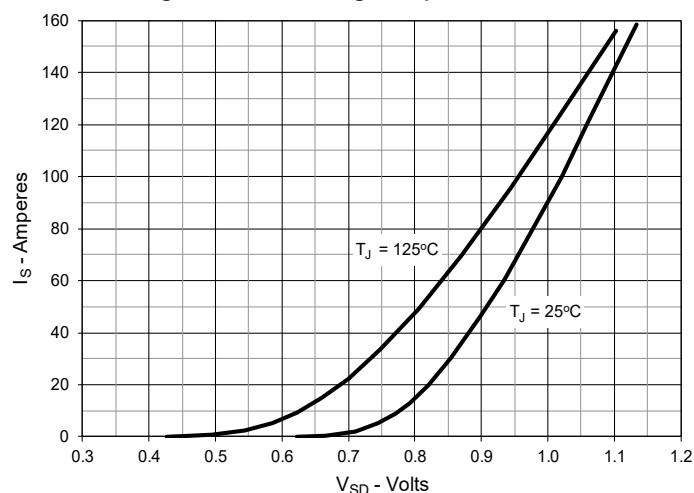


Fig. 10. Gate Charge

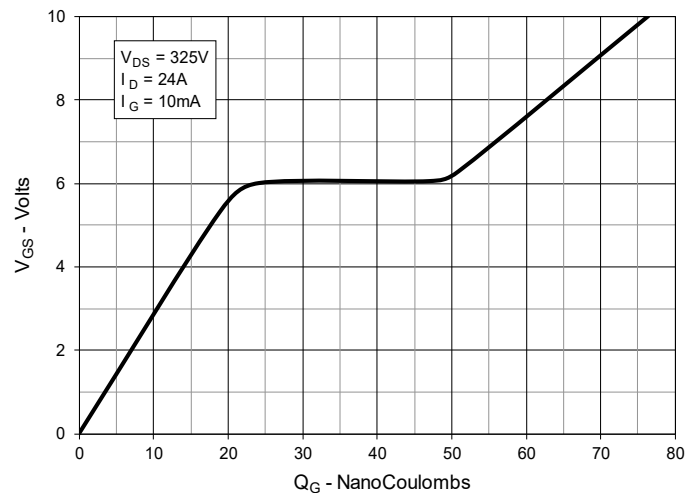


Fig. 11. Capacitance

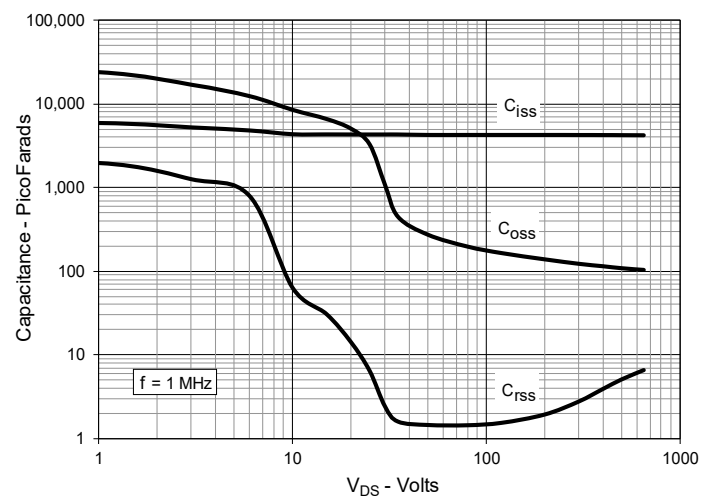


Fig. 12. Output Capacitance Stored Energy

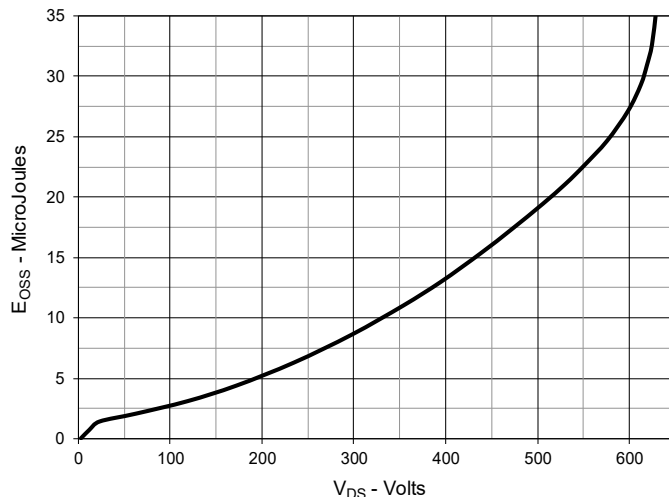


Fig. 13. Forward-Bias Safe Operating Area

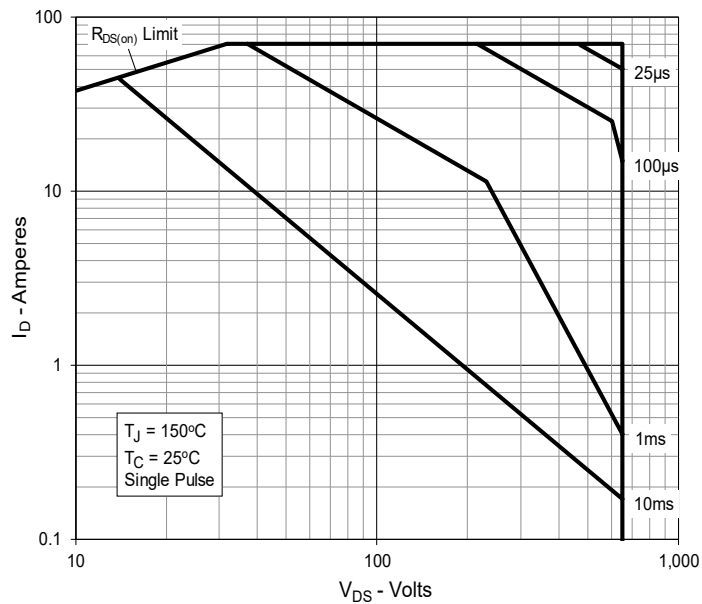
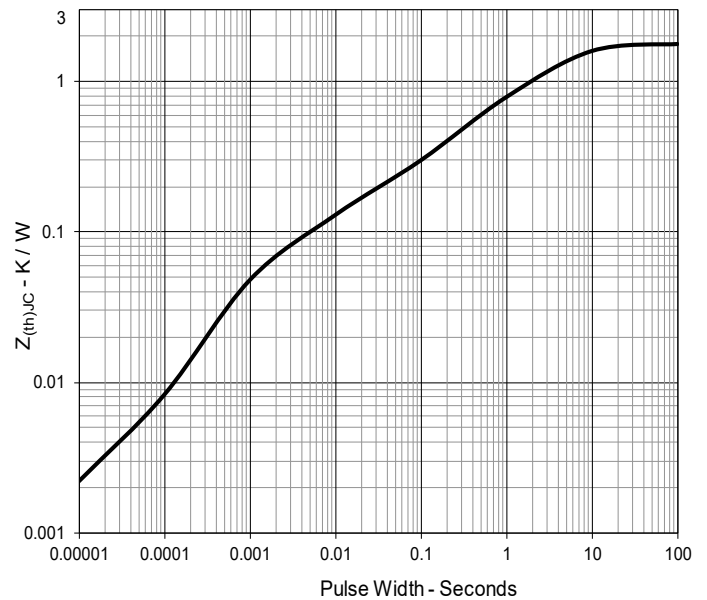
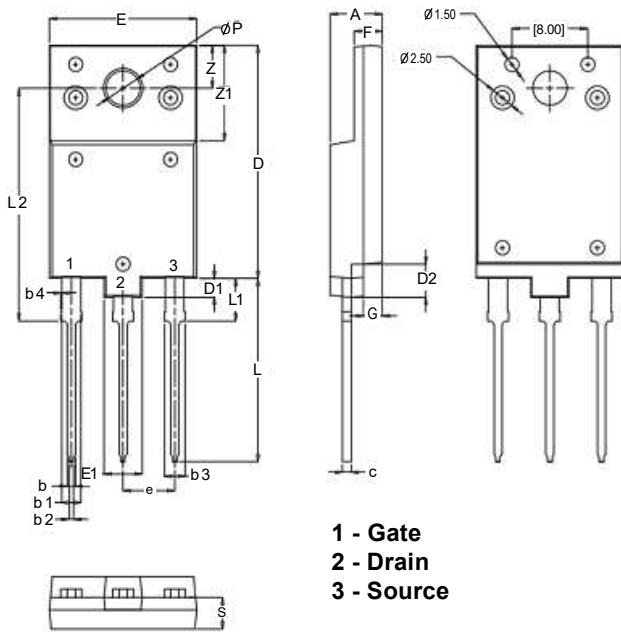


Fig. 14. Maximum Transient Thermal Impedance



TO-3PFP Outline



SYMBOL	MIN	MAX
A	5.30	5.70
b	0.65	0.95
b1	1.81	2.19
b2	0.30	0.70
b3	1.81	2.40
b4	-	0.20
c	0.80	1.00
D	24.20	24.80
D1	1.80	2.20
D2	3.30	3.70
E	15.30	15.70
E1	3.80	4.20
F	2.80	3.20
e	5.45 BSC	
L	19.00	19.60
L1	4.20	4.80
L2	24.20	24.80
P	3.40	3.80
Z	4.30	4.70
Z1	9.70	10.30
G	1.80	2.20
S	3.10	3.50

